GAP PADS
TCGF-HR-SERIES 5,0 W/m*K

TCGF- HR- Series is high rebound thermally conductive interface material. Due to their high compressibility and elasticity, they are particularly suitable for contacting very uneven surfaces.
Heat can transmit to the metal housing or dissipation plate from the separate elements or even the entire PCB, which in effect enhances the efficiency and lifetime of the heat-generating electronic components.
Gap fillers are based on silicone and are filled with ceramic particles. They are both sides tacky by nature.

- **Thermal conductivity: 5,0 W/m*K**
- **HR = High Rebound**
- **Available in 297x210 mm standard sheet size, other dimensions and die-cut parts on request**
- **Available in thicknesses from 0,5 to 10,0 mm**
- **Naturally both side tacky as standard, other options available**
- **Adhesive tape on request**
- **Based on silicone filled with ceramic particles**

RoHS ✓ REACH ✓ UL 94

PRODUCT SPECIFICATIONS

PROPERTY	VALUE / TOLERANCE	TEST METHOD
THERMAL		
Thermal conductivity	5,0 W/m*K	ASTM D5470
ELECTRICAL		
Breakdown voltage	>10 kV/mm	ASTM D149
Dielectric constant	4,7 MHz	ASTM D150
Volume resistivity	$0{,}95*10^{13}\Omega*cm$	ASTM D257
PHYSICAL		
Composition	Silicone elastomer	-
Hardness	25– 40 Shore 00 ± 10 %	ASTM D2240
Gravity	$3{,}1\ g/cm^3$	ASTM D792
Color	Multi-color	Visual
Tensile strength	25Psi	ASTM D412
Working temperature	-40 – 200 °C	-
Flammability rating	V-0	UL 94
Standard sheet size	297*210mm	-

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BUILDING AN ITEM NUMBER

TCGF-5,0 SxxHR#-LxWxT-XXX-YYY-ZZ

Thermally Conductive Gap Filler	
Thermal conductivity	
xx	Hardness (Shore 00)
F	Fiberglass reinforced
X	Not reinforced
xxx	Length (mm)
xxx	Width (mm)
xxx	Thickness (mm)
SST	One side tacky, one side non-tacky
BST	Both sides tacky
SAN	One side adhesive, one side non-tacky
SAT	One side adhesive, one side tacky
BSA	Both sides adhesive
DST	Die-cut parts
KCT	Kiss-cut parts
E1	ESD foil (single side)
E2	ESD foil (both sides)

Standard options

EXAMPLE

TCGF-5,0 S30HRF-35x17x5-BST-DST-E1
Thermally conductive gap filler high- rebound; thermal conductivity: 5,0 W/m*K; hardness: 30 Shore 00; fiberglass reinforced; size: 35x17 mm; thickness: 5 mm; both sides tacky; die-cut; ESD foil (single side)

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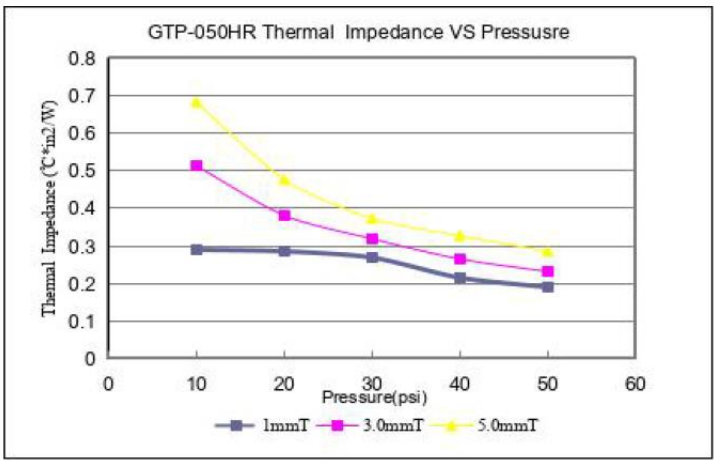
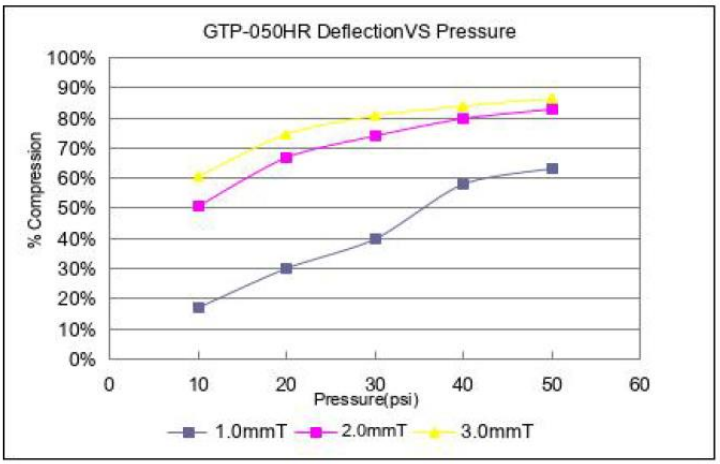
THERMAL IMPEDANCE vs. PRESSURE



COMPRESSIBILITY



STANDARD THICKNESSES (mm)

0,5 – 10mm

STANDARD HARDNESSES

25 Shore 00 | 30 Shore 00 | 40 Shore 00

TOLERANCES

THICKNESS		WIDTH AND HEIGTH	
0 – 0,50 mm	+/- 0,05 mm	0 – 50 mm	+/- 0,5 mm
0,60 – 10 mm	+/- 10%	> 50 mm	+/- 1,0 mm